

# **QTLP611CEB** Low V<sub>F</sub> Blue **Surface Mount LED Lamp, Compact Right Angle**

#### **Features**

- Miniature footprint 2.1(L) X 1.0(W) X 0.6(H) mm
- Wide viewing angle of 130°
- Water clear optics
- Available in 0.315" (8mm) width tape on 7" (178mm) diameter reel; 2,000 units per reel

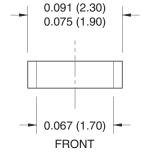
# **Description**

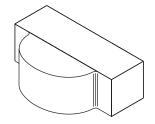
This compact right angle surface mount chip LED emits light in the lateral direction. Miniature size and wide viewing angle make this LED an ideal choice for edgelighting LCD displays. This device utilizes an InGaN/Sapphire blue LED.

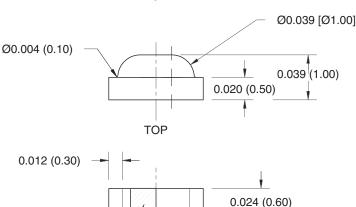
# **Applications**

- LCD edge-lighting
- Edge card lighting

# **Package Dimensions**









#### Note:

Dimensions for all drawings are in inches (mm).

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# **Absolute Maximum Ratings** ( $T_A = 25^{\circ}C$ Unless otherwise specified)

Parameter	Symbol	Rating	Unit
Operating Temperature	T <sub>OPR</sub>	-40 to +85	°C
Storage Temperature	T <sub>STG</sub>	-40 to +90	°C
Lead Soldering Time	T <sub>SOL</sub>	260 for 5 sec	°C
Continuous Forward Current	I <sub>F</sub>	30	mA
Peak Forward Current (f = 1.0 KHz, Duty Factor = 1/10)	I <sub>FM</sub>	100	mA
Reverse Voltage	V <sub>R</sub>	5	V
Power Dissipation	P <sub>D</sub>	80	mW

# **Electrical/Optical Characteristics** $(T_A = 25^{\circ}C)$

Part Number	QTLP611CEB	Condition
Luminous Intensity (mcd)		
Bin I2	8 – 16	I <sub>F</sub> = 5mA
Bin I3	13 – 26	
Forward Voltage (V)		
Bin V1	2.75 – 2.95	I <sub>F</sub> = 5mA
Bin V2	2.95 – 3.15	
Dominant Wavelength (nm)		
Bin W2	470 – 475	I <sub>F</sub> = 5mA
Bin W3	475 – 480	
Spectral Line Half Width (nm)	35	IF = 5mA
Viewing Angle (°)	130	IF = 5mA

# **Typical Performance Curves**

Fig. 1 Forward Current vs. Forward Voltage

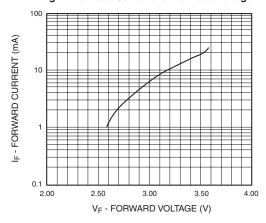


Fig. 2 Relative Luminous Intensity vs. DC Forward Current

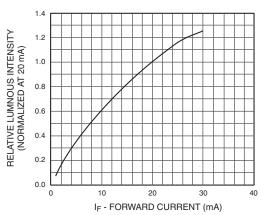


Fig. 3 Relative Intensity vs. Peak Wavelength

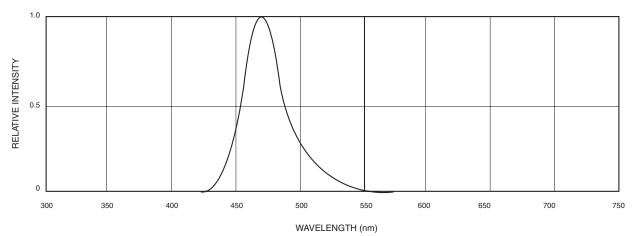


Fig.4 Radiation Diagram

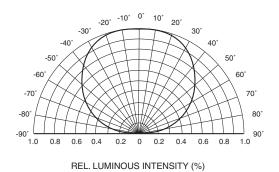
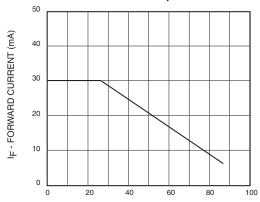
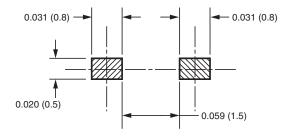


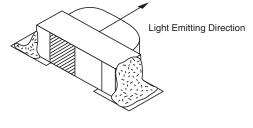
Fig.5 Maximum Forward Current vs. Ambient Temperature



T<sub>A</sub> - AMBIENT TEMPERATURE (°C)

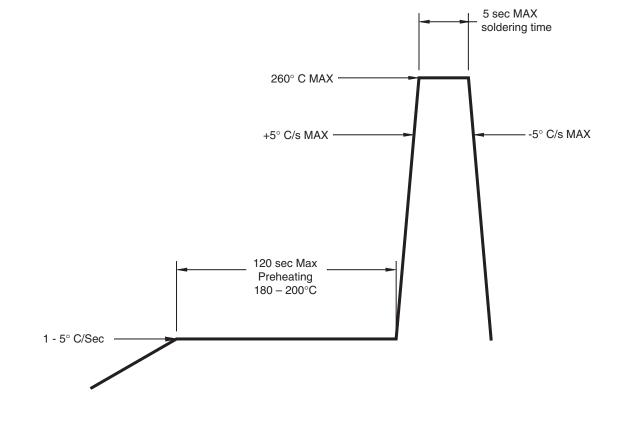
## **Recommended Printed Circuit Board Pattern**



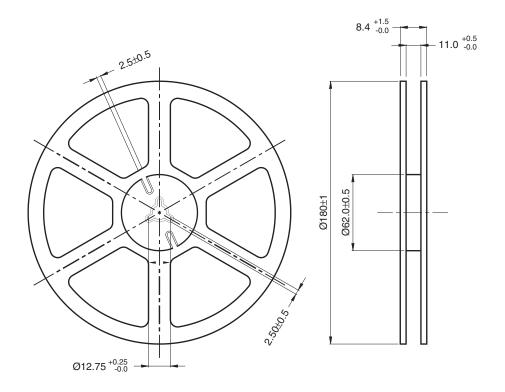


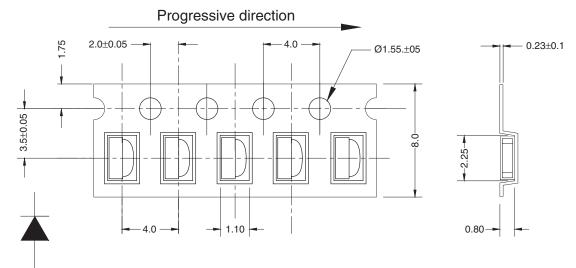
Mounting Example

# **Recommended IR Reflow Soldering Profile**



## TAPE AND REEL DIMENSIONS





Polarity Dimensional tolerance is  $\pm$  0.1mm unless otherwise specified

Angle: ± 0.5

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EcoSPARK™	I <sup>2</sup> C <sup>TM</sup>	MSXPro™	RapidConnect™	UltraFET <sup>®</sup>
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FACT™	IntelliMAX™	OPTOLOGIC®	SILENT SWITCHER®	Wire™
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		POP™	Stealth™	
		Power247™	SuperFET™	
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